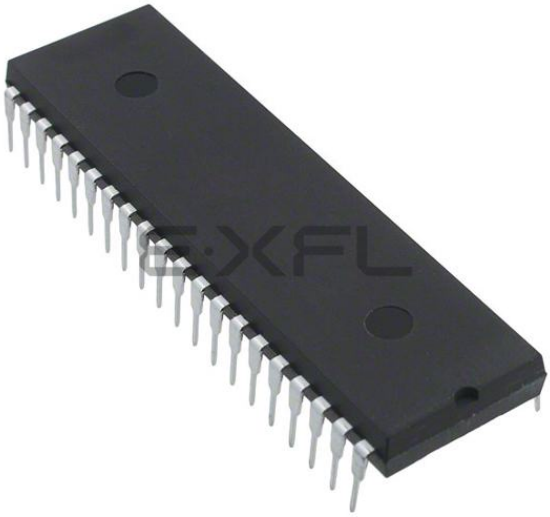

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Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 30x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf45k22-e-p

2.3 Register Definitions: Oscillator Control

REGISTER 2-1: OSCCON: OSCILLATOR CONTROL REGISTER

R/W-0	R/W-0	R/W-1	R/W-1	R-q	R-0	R/W-0	R/W-0
IDLEN	IRCF<2:0>			OSTS(1)	HFIOFS	SCS<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	q = depends on condition
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **IDLEN:** Idle Enable bit
1 = Device enters Idle mode on SLEEP instruction
0 = Device enters Sleep mode on SLEEP instruction

bit 6-4 **IRCF<2:0>:** Internal RC Oscillator Frequency Select bits(2)
111 = HFINTOSC – (16 MHz)
110 = HFINTOSC/2 – (8 MHz)
101 = HFINTOSC/4 – (4 MHz)
100 = HFINTOSC/8 – (2 MHz)
011 = HFINTOSC/16 – (1 MHz)(3)

If INTSRC = 0 and MFIOSEL = 0:
010 = HFINTOSC/32 – (500 kHz)
001 = HFINTOSC/64 – (250 kHz)
000 = LFINTOSC – (31.25 kHz)

If INTSRC = 1 and MFIOSEL = 0:
010 = HFINTOSC/32 – (500 kHz)
001 = HFINTOSC/64 – (250 kHz)
000 = HFINTOSC/512 – (31.25 kHz)

If INTSRC = 0 and MFIOSEL = 1:
010 = MFINTOSC – (500 kHz)
001 = MFINTOSC/2 – (250 kHz)
000 = LFINTOSC – (31.25 kHz)

If INTSRC = 1 and MFIOSEL = 1:
010 = MFINTOSC – (500 kHz)
001 = MFINTOSC/2 – (250 kHz)
000 = MFINTOSC/16 – (31.25 kHz)

bit 3 **OSTS:** Oscillator Start-up Time-out Status bit
1 = Device is running from the clock defined by FOSC<3:0> of the CONFIG1H register
0 = Device is running from the internal oscillator (HFINTOSC, MFINTOSC or LFINTOSC)

bit 2 **HFIOFS:** HFINTOSC Frequency Stable bit
1 = HFINTOSC frequency is stable
0 = HFINTOSC frequency is not stable

bit 1-0 **SCS<1:0>:** System Clock Select bit
1x = Internal oscillator block
01 = Secondary (SOSC) oscillator
00 = Primary clock (determined by FOSC<3:0> in CONFIG1H).

Note 1: Reset state depends on state of the IESO Configuration bit.
2: INTOSC source may be determined by the INTSRC bit in OSCTUNE and the MFIOSEL bit in OSCCON2.
3: Default output frequency of HFINTOSC on Reset.

2.9 Effects of Power-Managed Modes on the Various Clock Sources

For more information about the modes discussed in this section see **Section 3.0 "Power-Managed Modes"**. A quick reference list is also available in Table 3-1.

When PRI_IDLE mode is selected, the designated primary oscillator continues to run without interruption. For all other power-managed modes, the oscillator using the OSC1 pin is disabled. The OSC1 pin (and OSC2 pin, if used by the oscillator) will stop oscillating.

In secondary clock modes (SEC_RUN and SEC_IDLE), the secondary oscillator (SOSC) is operating and providing the device clock. The secondary oscillator may also run in all power-managed modes if required to clock Timer1, Timer3 or Timer5.

In internal oscillator modes (INTOSC_RUN and INTOSC_IDLE), the internal oscillator block provides the device clock source. The 31.25 kHz LFINTOSC output can be used directly to provide the clock and may be enabled to support various special features, regardless of the power-managed mode (see **Section 24.3 "Watchdog Timer (WDT)"**, **Section 2.12 "Two-Speed Clock Start-up Mode"** and **Section 2.13 "Fail-Safe Clock Monitor"** for more information on WDT, Fail-Safe Clock Monitor and Two-Speed Start-up). The HFINTOSC and MFINTOSC outputs may be used directly to clock the device or may be divided down by the postscaler. The HFINTOSC and MFINTOSC outputs are disabled when the clock is provided directly from the LFINTOSC output.

When the Sleep mode is selected, all clock sources are stopped. Since all the transistor switching currents have been stopped, Sleep mode achieves the lowest current consumption of the device (only leakage currents).

Enabling any on-chip feature that will operate during Sleep will increase the current consumed during Sleep. The LFINTOSC is required to support WDT operation. Other features may be operating that do not require a device clock source (i.e., SSP slave, PSP, INTn pins and others). Peripherals that may add significant current consumption are listed in **Section 27.8 "DC Characteristics: Input/Output Characteristics, PIC18(L)F2X/4XK22".**

2.10 Power-up Delays

Power-up delays are controlled by two timers, so that no external Reset circuitry is required for most applications. The delays ensure that the device is kept in Reset until the device power supply is stable under normal circumstances and the primary clock is operating and stable. For additional information on power-up delays, see **Section 4.6 "Device Reset Timers"**.

The first timer is the Power-up Timer (PWRT), which provides a fixed delay on power-up. It is enabled by clearing (= 0) the PWRTEN Configuration bit.

The second timer is the Oscillator Start-up Timer (OST), intended to keep the chip in Reset until the crystal oscillator is stable (LP, XT and HS modes). The OST does this by counting 1024 oscillator cycles before allowing the oscillator to clock the device.

When the PLL is enabled with external oscillator modes, the device is kept in Reset for an additional 2 ms, following the OST delay, so the PLL can lock to the incoming clock frequency.

There is a delay of interval T_{CSD}, following POR, while the controller becomes ready to execute instructions. This delay runs concurrently with any other delays. This may be the only delay that occurs when any of the EC, RC or INTIOSC modes are used as the primary clock source.

When the HFINTOSC is selected as the primary clock, the main system clock can be delayed until the HFINTOSC is stable. This is user selectable by the HFOFST bit of the CONFIG3H Configuration register. When the HFOFST bit is cleared, the main system clock is delayed until the HFINTOSC is stable. When the HFOFST bit is set, the main system clock starts immediately.

In either case, the HFIOFS bit of the OSCCON register can be read to determine whether the HFINTOSC is operating and stable.

3.0 POWER-MANAGED MODES

PIC18(L)F2X/4XK22 devices offer a total of seven operating modes for more efficient power management. These modes provide a variety of options for selective power conservation in applications where resources may be limited (i.e., battery-powered devices).

There are three categories of power-managed modes:

- Run modes
- Idle modes
- Sleep mode

These categories define which portions of the device are clocked and sometimes, what speed. The Run and Idle modes may use any of the three available clock sources (primary, secondary or internal oscillator block). The Sleep mode does not use a clock source.

The power-managed modes include several power-saving features offered on previous PIC® microcontroller devices. One of the clock switching features allows the controller to use the secondary oscillator (SOSC) in place of the primary oscillator. Also included is the Sleep mode, offered by all PIC microcontroller devices, where all device clocks are stopped.

3.1 Selecting Power-Managed Modes

Selecting a power-managed mode requires two decisions:

- Whether or not the CPU is to be clocked
- The selection of a clock source

The IDLEN bit (OSCCON<7>) controls CPU clocking, while the SCS<1:0> bits (OSCCON<1:0>) select the clock source. The individual modes, bit settings, clock sources and affected modules are summarized in Table 3-1.

3.1.1 CLOCK SOURCES

The SCS<1:0> bits allow the selection of one of three clock sources for power-managed modes. They are:

- the primary clock, as defined by the FOSC<3:0> Configuration bits
- the secondary clock (the SOSC oscillator)
- the internal oscillator block

3.1.2 ENTERING POWER-MANAGED MODES

Switching from one power-managed mode to another begins by loading the OSCCON register. The SCS<1:0> bits select the clock source and determine which Run or Idle mode is to be used. Changing these bits causes an immediate switch to the new clock source, assuming that it is running. The switch may also be subject to clock transition delays. Refer to **Section 2.11 “Clock Switching”** for more information.

Entry to the power-managed Idle or Sleep modes is triggered by the execution of a SLEEP instruction. The actual mode that results depends on the status of the IDLEN bit.

Depending on the current mode and the mode being switched to, a change to a power-managed mode does not always require setting all of these bits. Many transitions may be done by changing the oscillator select bits, or changing the IDLEN bit, prior to issuing a SLEEP instruction. If the IDLEN bit is already configured correctly, it may only be necessary to perform a SLEEP instruction to switch to the desired mode.

TABLE 3-1: POWER-MANAGED MODES

Mode	OSCCON Bits		Module Clocking		Available Clock and Oscillator Source
	IDLEN(1)	SCS<1:0>	CPU	Peripherals	
Sleep	0	N/A	Off	Off	None – All clocks are disabled
PRI_RUN	N/A	00	Clocked	Clocked	Primary – LP, XT, HS, RC, EC and Internal Oscillator Block(2). This is the normal full-power execution mode.
SEC_RUN	N/A	01	Clocked	Clocked	Secondary – SOSC Oscillator
RC_RUN	N/A	1x	Clocked	Clocked	Internal Oscillator Block(2)
PRI_IDLE	1	00	Off	Clocked	Primary – LP, XT, HS, HSPLL, RC, EC
SEC_IDLE	1	01	Off	Clocked	Secondary – SOSC Oscillator
RC_IDLE	1	1x	Off	Clocked	Internal Oscillator Block(2)

Note 1: IDLEN reflects its value when the SLEEP instruction is executed.

2: Includes HFINTOSC and HFINTOSC postscaler, as well as the LFINTOSC source.

4.0 RESET

The PIC18(L)F2X/4XK22 devices differentiate between various kinds of Reset:

a) Power-on Reset (POR)
b) $\overline{\text{MCLR}}$ Reset during normal operation
c) $\overline{\text{MCLR}}$ Reset during power-managed modes
d) Watchdog Timer (WDT) Reset (during execution)
e) Programmable Brown-out Reset (BOR)
f) RESET Instruction
g) Stack Full Reset
h) Stack Underflow Reset

This section discusses Resets generated by $\overline{\text{MCLR}}$, POR and BOR and covers the operation of the various start-up timers. Stack Reset events are covered in **Section 5.2.0.1 "Stack Full and Underflow Resets"**. WDT Resets are covered in **Section 24.3 "Watchdog Timer (WDT)"**.

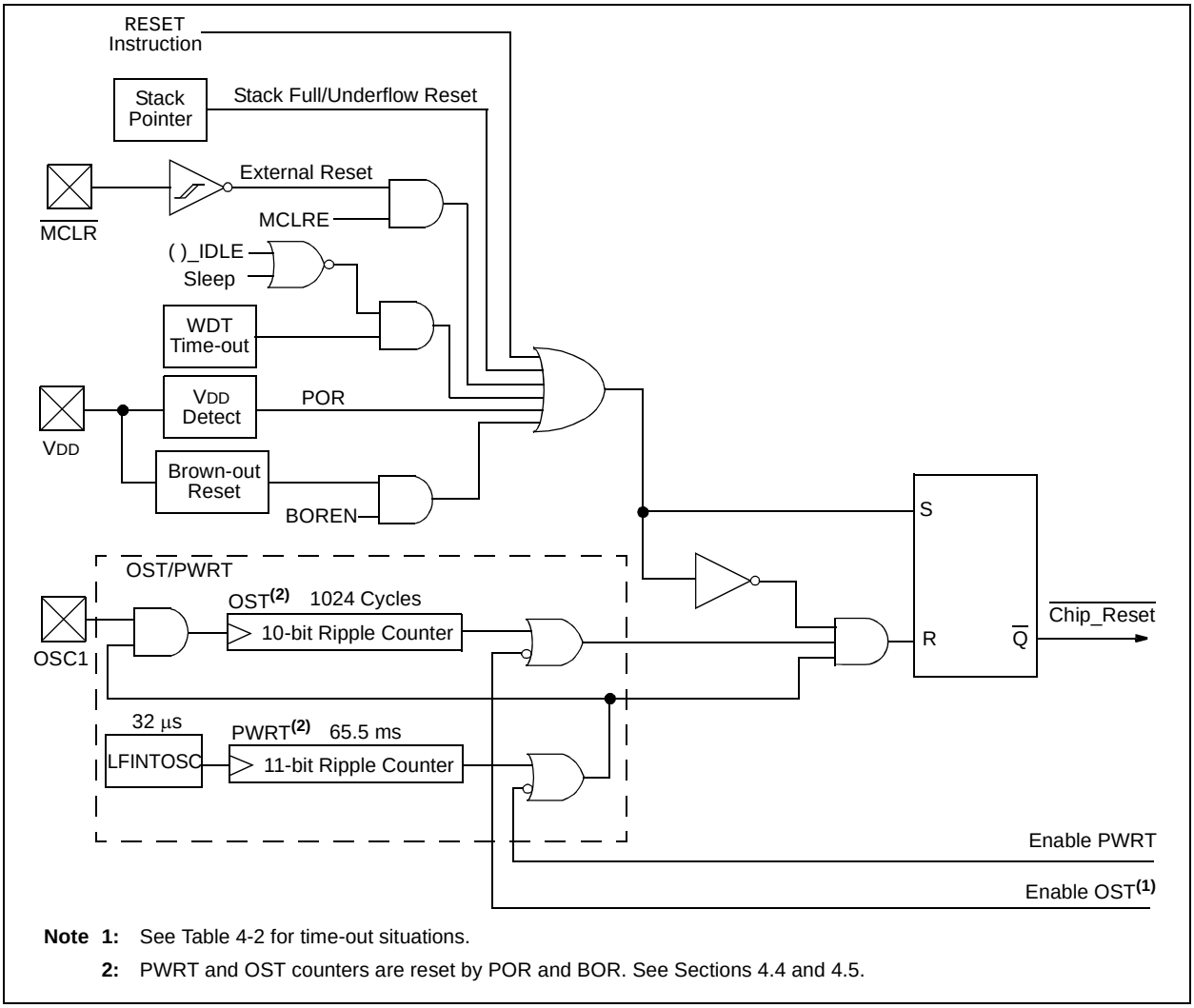
A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 4-1.

4.1 RCON Register

Device Reset events are tracked through the RCON register (Register 4-1). The lower five bits of the register indicate that a specific Reset event has occurred. In most cases, these bits can only be cleared by the event and must be set by the application after the event. The state of these flag bits, taken together, can be read to indicate the type of Reset that just occurred. This is described in more detail in **Section 4.7 "Reset State of Registers"**.

The RCON register also has control bits for setting interrupt priority (IPEN) and software control of the BOR (SBOREN). Interrupt priority is discussed in **Section 9.0 "Interrupts"**. BOR is covered in **Section 4.5 "Brown-out Reset (BOR)"**.

FIGURE 4-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



Note 1: See Table 4-2 for time-out situations.

2: PWRT and OST counters are reset by POR and BOR. See Sections 4.4 and 4.5.

TABLE 4-1: BOR CONFIGURATIONS

BOR Configuration		Status of SBOREN (RCON<6>)	BOR Operation
BOREN1	BOREN0		
0	0	Unavailable	BOR disabled; must be enabled by reprogramming the Configuration bits.
0	1	Available	BOR enabled by software; operation controlled by SBOREN.
1	0	Unavailable	BOR enabled by hardware in Run and Idle modes, disabled during Sleep mode.
1	1	Unavailable	BOR enabled by hardware; must be disabled by reprogramming the Configuration bits.

4.6 Device Reset Timers

PIC18(L)F2X/4XK22 devices incorporate three separate on-chip timers that help regulate the Power-on Reset process. Their main function is to ensure that the device clock is stable before code is executed. These timers are:

- Power-up Timer (PWRT)
- Oscillator Start-up Timer (OST)
- PLL Lock Time-out

4.6.1 POWER-UP TIMER (PWRT)

The Power-up Timer (PWRT) of PIC18(L)F2X/4XK22 devices is an 11-bit counter which uses the LFINTOSC source as the clock input. This yields an approximate time interval of 2048 x 32 μs = 65.6 ms. While the PWRT is counting, the device is held in Reset.

The power-up time delay depends on the LFINTOSC clock and will vary from chip-to-chip due to temperature and process variation.

The PWRT is enabled by clearing the $\overline{\text{PWRTEN}}$ Configuration bit.

4.6.2 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-up Timer (OST) provides a 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures that the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset, or on exit from all power-managed modes that stop the external oscillator.

4.6.3 PLL LOCK TIME-OUT

With the PLL enabled, the time-out sequence following a Power-on Reset is slightly different from other oscillator modes. A separate timer is used to provide a fixed time-out that is sufficient for the PLL to lock to the main oscillator frequency. This PLL lock time-out (T_{PLL}) is typically 2 ms and follows the oscillator start-up time-out.

4.6.4 TIME-OUT SEQUENCE

On power-up, the time-out sequence is as follows:

1. After the POR pulse has cleared, PWRT time-out is invoked (if enabled).
2. Then, the OST is activated.

The total time-out will vary based on oscillator configuration and the status of the PWRT. Figure 4-3, Figure 4-4, Figure 4-5, Figure 4-6 and Figure 4-7 all depict time-out sequences on power-up, with the Power-up Timer enabled and the device operating in HS Oscillator mode. Figures 4-3 through 4-6 also apply to devices operating in XT or LP modes. For devices in RC mode and with the PWRT disabled, on the other hand, there will be no time-out at all.

Since the time-outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, all time-outs will expire, after which, bringing $\overline{\text{MCLR}}$ high will allow program execution to begin immediately (Figure 4-5). This is useful for testing purposes or to synchronize more than one PIC® MCU device operating in parallel.

6.3 Register Definitions: Memory Control

REGISTER 6-1: EECON1: DATA EEPROM CONTROL 1 REGISTER

R/W-x	R/W-x	U-0	R/W-0	R/W-x	R/W-0	R/S-0	R/S-0
EEPGD	CFGS	—	FREE	WRERR	WREN	WR	RD
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit		
S = Bit can be set by software, but not cleared		U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **EEPGD:** Flash Program or Data EEPROM Memory Select bit
- 1 = Access Flash program memory
- 0 = Access data EEPROM memory

bit 6 **CFGS:** Flash Program/Data EEPROM or Configuration Select bit
- 1 = Access Configuration registers
- 0 = Access Flash program or data EEPROM memory

bit 5 **Unimplemented:** Read as '0'

bit 4 **FREE:** Flash Row (Block) Erase Enable bit
- 1 = Erase the program memory block addressed by TBLPTR on the next WR command (cleared by completion of erase operation)
- 0 = Perform write-only

bit 3 **WRERR:** Flash Program/Data EEPROM Error Flag bit(1)
- 1 = A write operation is prematurely terminated (any Reset during self-timed programming in normal operation, or an improper write attempt)
- 0 = The write operation completed

bit 2 **WREN:** Flash Program/Data EEPROM Write Enable bit
- 1 = Allows write cycles to Flash program/data EEPROM
- 0 = Inhibits write cycles to Flash program/data EEPROM

bit 1 **WR:** Write Control bit
- 1 = Initiates a data EEPROM erase/write cycle or a program memory erase cycle or write cycle. (The operation is self-timed and the bit is cleared by hardware once write is complete. The WR bit can only be set (not cleared) by software.)
- 0 = Write cycle to the EEPROM is complete

bit 0 **RD:** Read Control bit
- 1 = Initiates an EEPROM read (Read takes one cycle. RD is cleared by hardware. The RD bit can only be set (not cleared) by software. RD bit cannot be set when EEPGD = 1 or CFGS = 1.)
- 0 = Does not initiate an EEPROM read

Note 1: When a WRERR occurs, the EEPGD and CFGS bits are not cleared. This allows tracing of the error condition.

A mismatch condition will continue to set the RBIF flag bit. Reading or writing PORTB will end the mismatch condition and allow the RBIF bit to be cleared. The latch holding the last read value is not affected by a MCLR nor Brown-out Reset. After either one of these Resets, the RBIF flag will continue to be set if a mismatch is present.

Note:	If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set. Furthermore, since a read or write on a port affects all bits of that port, care must be taken when using multiple pins in Interrupt-on-change mode. Changes on one pin may not be seen while servicing changes on another pin.

The interrupt-on-change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt-on-change feature. Polling of PORTB is not recommended while using the interrupt-on-change feature.

10.3.3 ALTERNATE FUNCTIONS

PORTB is multiplexed with several peripheral functions (Table 10-5). The pins have TTL input buffers. Some of these pin functions can be relocated to alternate pins using the Control fuse bits in CONFIG3H. RB5 is the default pin for P2B (28-pin devices). Clearing the P2BMX bit moves the pin function to RC0. RB5 is also the default pin for the CCP3/P3A peripheral pin. Clearing the CCP3MX bit moves the pin function to the RC6 pin (28-pin devices) or RE0 (40/44-pin devices).

Two other pin functions, T3CKI and CCP2/P2A, can be relocated from their default pins to PORTB pins by clearing the control fuses in CONFIG3H. Clearing T3CMX and CCP2MX moves the pin functions to RB5 and RB3, respectively.

TABLE 10-5: PORTB I/O SUMMARY

Pin	Function	TRIS Setting	ANSEL Setting	Pin Type	Buffer Type	Description
RB0/INT0/CCP4/ FLT0/SRI/SS2/ AN12	RB0	0	0	O	DIG	LATB<0> data output; not affected by analog input.
		1	0	I	TTL	PORTB<0> data input; disabled when analog input enabled.
	INT0	1	0	I	ST	External interrupt 0.
	CCP4(3)	0	0	O	DIG	Compare 4 output/PWM 4 output.
		1	0	I	ST	Capture 4 input.
	FLT0	1	0	I	ST	PWM Fault input for ECCP auto-shutdown.
	SRI	1	0	I	ST	SR latch input.
	SS2(3)	1	0	I	TTL	SPI slave select input (MSSP2).
	AN12	1	1	I	AN	Analog input 12.
RB1/INT1/P1C/ SCK2/SCL2/ C12IN3-/AN10	RB1	0	0	O	DIG	LATB<1> data output; not affected by analog input.
		1	0	I	TTL	PORTB<1> data input; disabled when analog input enabled.
	INT1	1	0	I	ST	External Interrupt 1.
	P1C(3)	0	0	O	DIG	Enhanced CCP1 PWM output 3.
	SCK2(3)	0	0	O	DIG	MSSP2 SPI Clock output.
		1	0	I	ST	MSSP2 SPI Clock input.
	SCL2(3)	0	0	O	DIG	MSSP2 I^2C Clock output.
		1	0	I	I^2C	MSSP2 I^2C Clock input.
	C12IN3-	1	1	I	AN	Comparators C1 and C2 inverting input.
	AN10	1	1	I	AN	Analog input 10.

Legend: AN = Analog input or output; TTL = TTL compatible input; HV = High Voltage; OD = Open Drain; XTAL = Crystal; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I^2C = Schmitt Trigger input with I^2C.

Note 1: Default pin assignment for P2B, T3CKI, CCP3 and CCP2 when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are set.

2: Alternate pin assignment for P2B, T3CKI, CCP3 and CCP2 when Configuration bits PB2MX, T3CMX, CCP3MX and CCP2MX are clear.

3: Function on PORTD and PORTE for PIC18(L)F4XK22 devices.

12.1 Timer1/3/5 Operation

The Timer1/3/5 module is a 16-bit incrementing counter which is accessed through the TMRxH:TMRxL register pair. Writes to TMRxH or TMRxL directly update the counter.

When used with an internal clock source, the module is a timer and increments on every instruction cycle. When used with an external clock source, the module can be used as either a timer or counter and increments on every selected edge of the external source.

Timer1/3/5 is enabled by configuring the TMRxON and TMRxGE bits in the TxCON and TxGCON registers, respectively. Table 12-1 displays the Timer1/3/5 enable selections.

TABLE 12-1: TIMER1/3/5 ENABLE SELECTIONS

TMRxON	TMRxGE	Timer1/3/5 Operation
0	0	Off
0	1	Off
1	0	Always On
1	1	Count Enabled

12.2 Clock Source Selection

The TMRxCS<1:0> and TxSOSCEN bits of the TxCON register are used to select the clock source for Timer1/3/5. The dedicated Secondary Oscillator circuit can be used as the clock source for Timer1, Timer3 and Timer5, simultaneously. Any of the TxSOSCEN bits will enable the Secondary Oscillator circuit and select it as the clock source for that particular timer. Table 12-2 displays the clock source selections.

12.2.1 INTERNAL CLOCK SOURCE

When the internal clock source is selected the TMRxH:TMRxL register pair will increment on multiples of FOSC as determined by the Timer1/3/5 prescaler.

When the FOSC internal clock source is selected, the Timer1/3/5 register value will increment by four counts every instruction clock cycle. Due to this condition, a 2 LSB error in resolution will occur when reading the Timer1/3/5 value. To utilize the full resolution of Timer1/3/5, an asynchronous input signal must be used to gate the Timer1/3/5 clock input.

The following asynchronous sources may be used:

- Asynchronous event on the TxG pin to Timer1/3/5 Gate
- C1 or C2 comparator input to Timer1/3/5 Gate

12.2.2 EXTERNAL CLOCK SOURCE

When the external clock source is selected, the Timer1/3/5 module may work as a timer or a counter.

When enabled to count, Timer1/3/5 is incremented on the rising edge of the external clock input of the TxCKI pin. This external clock source can be synchronized to the microcontroller system clock or it can run asynchronously.

When used as a timer with a clock oscillator, an external 32.768 kHz crystal can be used in conjunction with the dedicated secondary internal oscillator circuit.

Note: In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge after any one or more of the following conditions:

- Timer1/3/5 enabled after POR
- Write to TMRxH or TMRxL
- Timer1/3/5 is disabled
- Timer1/3/5 is disabled (TMRxON = 0) when TxCKI is high then Timer1/3/5 is enabled (TMRxON=1) when TxCKI is low.

TABLE 12-2: CLOCK SOURCE SELECTIONS

TMRxCS1	TMRxCS0	TxSOSCEN	Clock Source
0	1	x	System Clock (FOSC)
0	0	x	Instruction Clock (FOSC/4)
1	0	0	External Clocking on TxCKI Pin
1	0	1	Osc.Circuit On SOSCI/SOSCO Pins

14.3 PWM Overview

Pulse-Width Modulation (PWM) is a scheme that provides power to a load by switching quickly between fully on and fully off states. The PWM signal resembles a square wave where the high portion of the signal is considered the on state and the low portion of the signal is considered the off state. The high portion, also known as the pulse width, can vary in time and is defined in steps. A larger number of steps applied, which lengthens the pulse width, also supplies more power to the load. Lowering the number of steps applied, which shortens the pulse width, supplies less power. The PWM period is defined as the duration of one complete cycle or the total amount of on and off time combined.

PWM resolution defines the maximum number of steps that can be present in a single PWM period. A higher resolution allows for more precise control of the pulse width time and in turn the power that is applied to the load.

The term duty cycle describes the proportion of the on time to the off time and is expressed in percentages, where 0% is fully off and 100% is fully on. A lower duty cycle corresponds to less power applied and a higher duty cycle corresponds to more power applied.

Figure 14-3 shows a typical waveform of the PWM signal.

14.3.1 STANDARD PWM OPERATION

The standard PWM function described in this section is available and identical for CCP and ECCP modules.

The standard PWM mode generates a Pulse-Width modulation (PWM) signal on the CCPx pin with up to 10 bits of resolution. The period, duty cycle, and resolution are controlled by the following registers:

- PRx registers
- TxCON registers
- CCPRxL registers
- CCPxCON registers

Figure 14-4 shows a simplified block diagram of PWM operation.

Note 1:	The corresponding TRIS bit must be cleared to enable the PWM output on the CCPx pin.
2:	Clearing the CCPxCON register will relinquish control of the CCPx pin.

FIGURE 14-3: CCP PWM OUTPUT SIGNAL

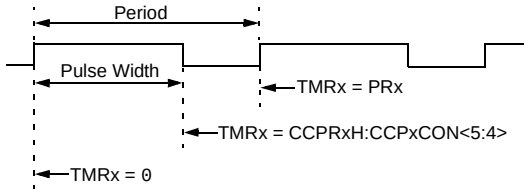
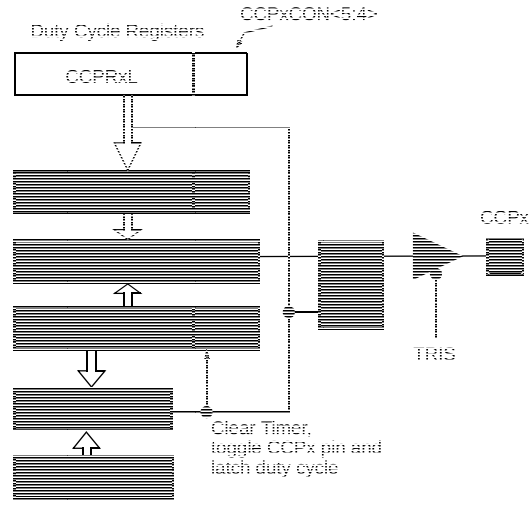


FIGURE 14-4: SIMPLIFIED PWM BLOCK DIAGRAM



Note 1: The 8-bit timer TMRx register is concatenated with the 2-bit internal system clock (Fosc), or 2 bits of the prescaler, to create the 10-bit time base.

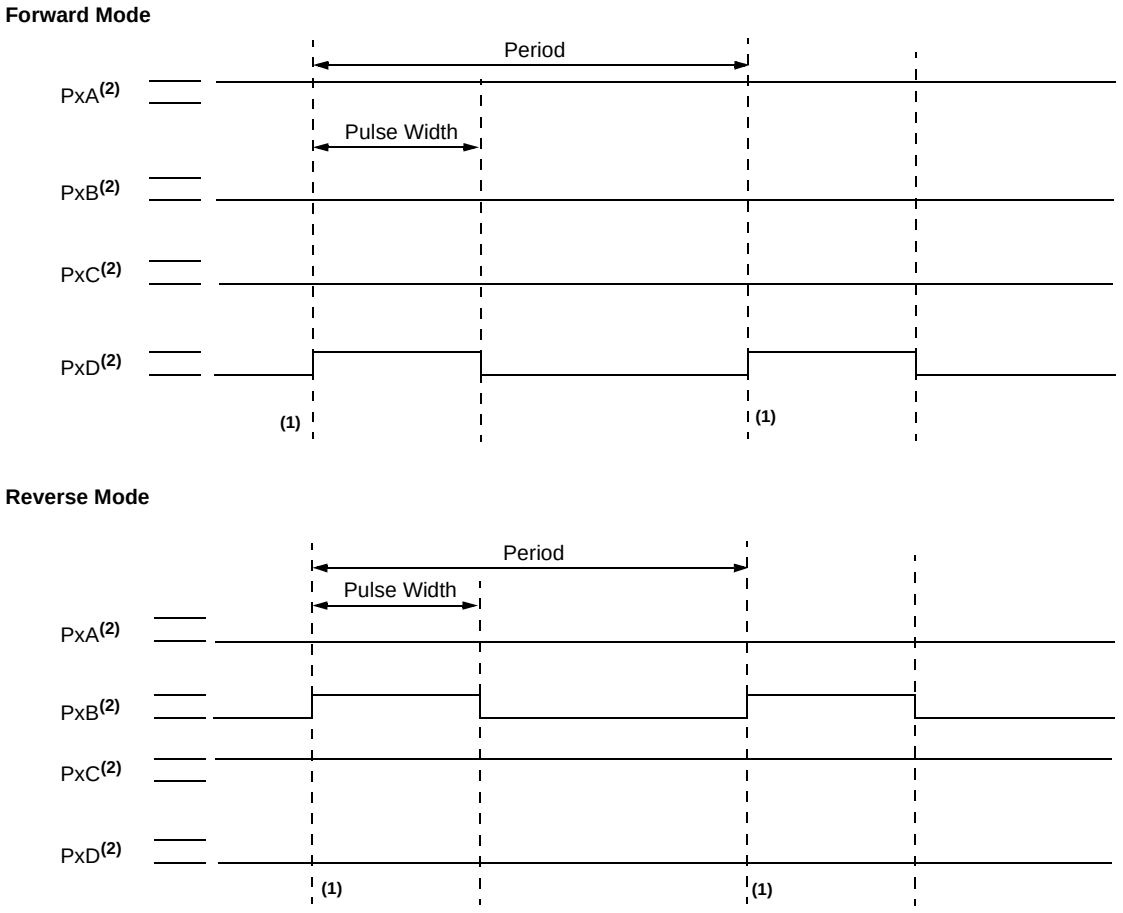
2: In PWM mode, CCPRxH is a read-only register.

14.3.2 SETUP FOR PWM OPERATION

The following steps should be taken when configuring the CCP module for standard PWM operation:

1. Disable the CCPx pin output driver by setting the associated TRIS bit.
2. Select the 8-bit TimerX resource, (Timer2, Timer4 or Timer6) to be used for PWM generation by setting the CxTSEL<1:0> bits in the CCPTMRSx register.(1)
3. Load the PRx register for the selected TimerX with the PWM period value.
4. Configure the CCP module for the PWM mode by loading the CCPxCON register with the appropriate values.
5. Load the CCPRxL register and the DCxB<1:0> bits of the CCPxCON register, with the PWM duty cycle value.

FIGURE 14-11: EXAMPLE OF FULL-BRIDGE PWM OUTPUT



Note 1: At this time, the TMRx register is equal to the PRx register.

2: Output signal is shown as active-high.

FIGURE 15-7: SPI DAISY-CHAIN CONNECTION

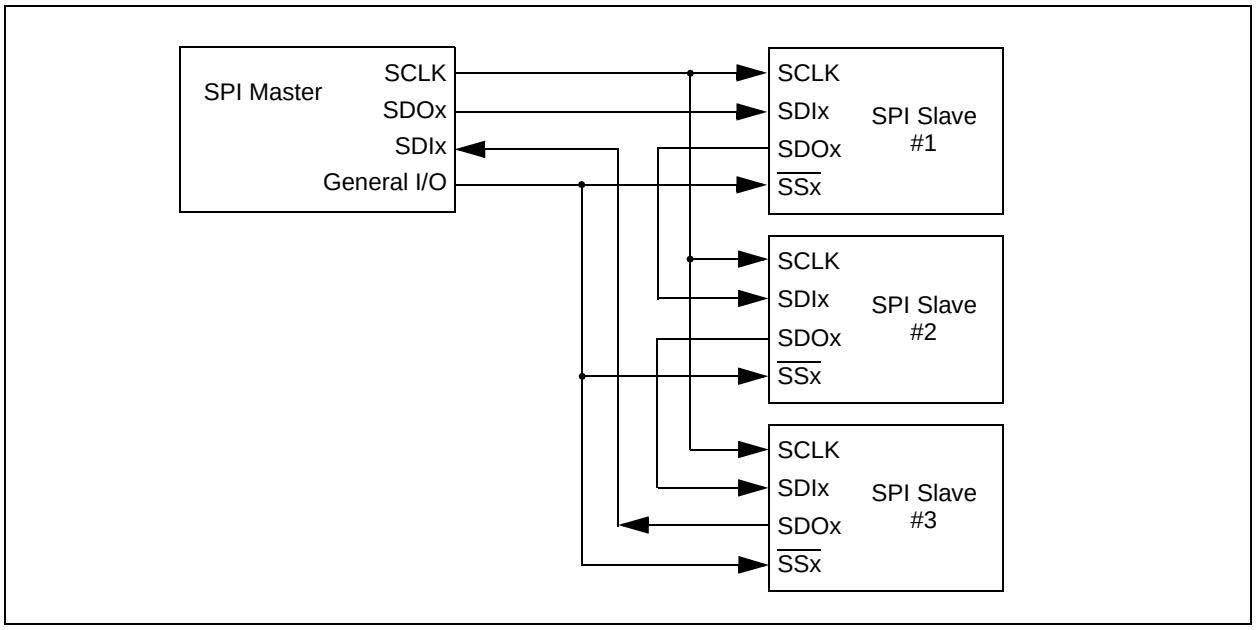
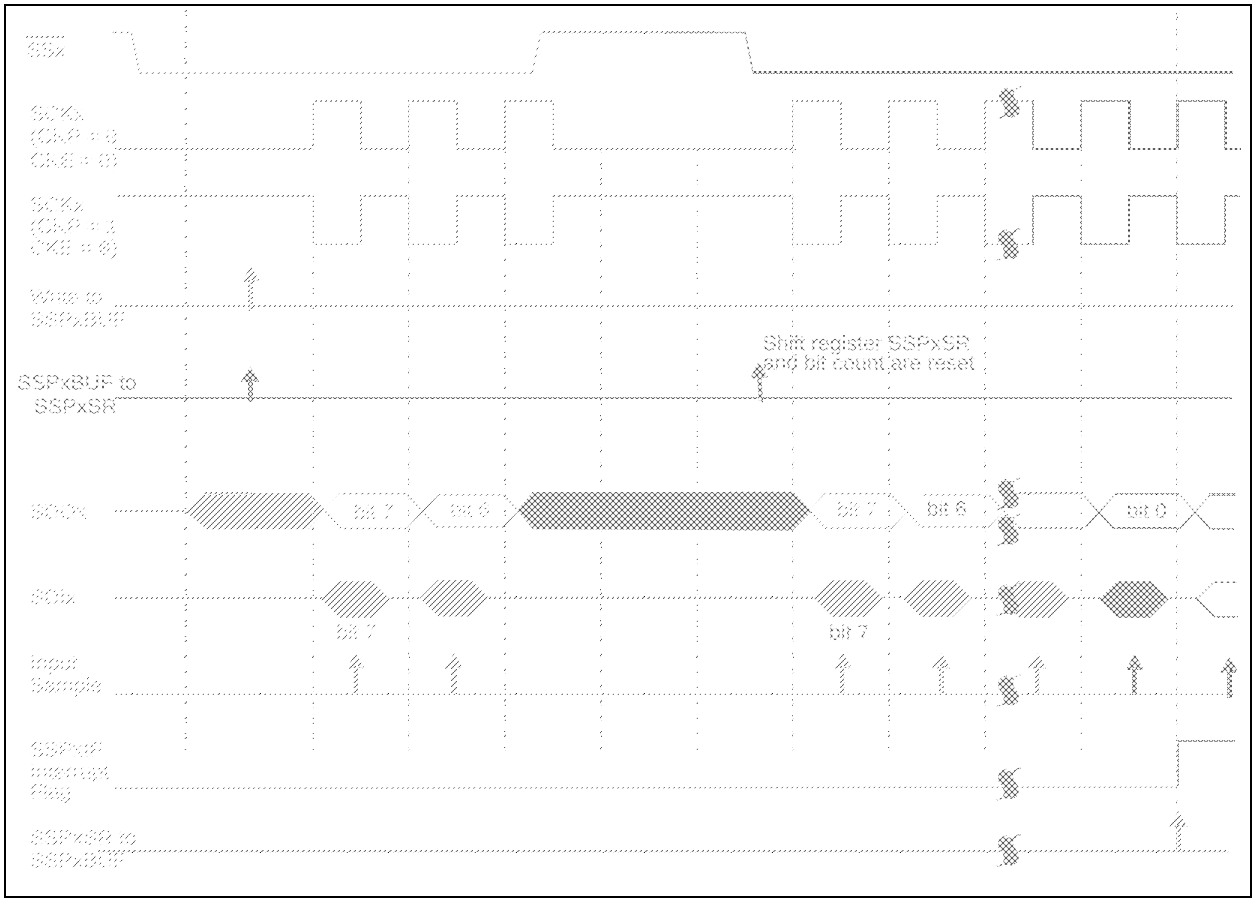


FIGURE 15-8: SLAVE SELECT SYNCHRONOUS WAVEFORM

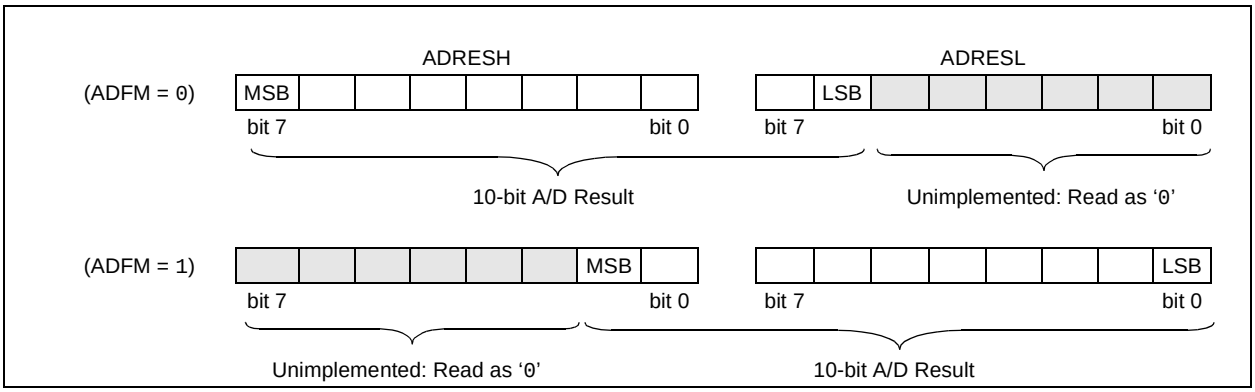


17.1.7 RESULT FORMATTING

The 10-bit A/D conversion result can be supplied in two formats, left justified or right justified. The ADFM bit of the ADCON2 register controls the output format.

Figure 17-2 shows the two output formats.

FIGURE 17-2: 10-BIT A/D CONVERSION RESULT FORMAT



17.4 A/D Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 17-5. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), see Figure 17-5. The maximum recommended impedance for analog sources is 3 kΩ. As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an A/D acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 17-1 may be used. This equation assumes that 1/2 LSb error is used (1024 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 17-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ $3.0V$ V_{DD}

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$
$$= 5\mu s + T_C + [(\text{Temperature} - 25°C)(0.05\mu s/°C)]$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{2047}\right) = V_{CHOLD} \quad ;[1]\ V_{CHOLD}\ \text{charged to within 1/2 lsb}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD} \quad ;[2]\ V_{CHOLD}\ \text{charge response to}\ V_{APPLIED}$$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{2047}\right) \quad ;\text{combining [1] and [2]}$$

Solving for T_C*:*

$$T_C = -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/2047)$$
$$= -13.5pF(1k\Omega + 700\Omega + 10k\Omega)\ ln(0.0004885)$$
$$= 1.20\mu s$$

Therefore:

$$T_{ACQ} = 5\mu s + 1.20\mu s + [(50°C - 25°C)(0.05\mu s/°C)]$$
$$= 7.45\mu s$$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

18.8 Additional Comparator Features

There are four additional comparator features:

- Simultaneous read of comparator outputs
- Internal reference selection
- Hysteresis selection
- Output Synchronization

18.8.1 SIMULTANEOUS COMPARATOR OUTPUT READ

The MC1OUT and MC2OUT bits of the CM2CON1 register are mirror copies of both comparator outputs. The ability to read both outputs simultaneously from a single register eliminates the timing skew of reading separate registers.

Note 1:	Obtaining the status of C1OUT or C2OUT by reading CM2CON1 does not affect the comparator interrupt mismatch registers.

18.8.2 INTERNAL REFERENCE SELECTION

There are two internal voltage references available to the non-inverting input of each comparator. One of these is the Fixed Voltage Reference (FVR) and the other is the variable Digital-to-Analog Converter (DAC). The CxRSEL bit of the CM2CON1 register determines which of these references is routed to the Comparator Voltage reference output (CxVREF). Further routing to the comparator is accomplished by the CxR bit of the CMxCON0 register. See **Section 21.0 “Fixed Voltage Reference (FVR)”** and Figure 18-2 for more detail.

18.8.3 COMPARATOR HYSTERESIS

Each Comparator has a selectable hysteresis feature. The hysteresis can be enabled by setting the CxHYS bit of the CM2CON1 register. See **Section 27.0 “Electrical Specifications”** for more details.

18.8.4 SYNCHRONIZING COMPARATOR OUTPUT TO TIMER1

The Comparator Cx output can be synchronized with Timer1 by setting the CxSYNC bit of the CM2CON1 register. When enabled, the Cx output is latched on the falling edge of the Timer1 source clock. To prevent a race condition when gating Timer1 clock with the comparator output, Timer1 increments on the rising edge of its clock source, and the falling edge latches the comparator output. See the Comparator Block Diagram (Figure 18-2) and the Timer1 Block Diagram (Figure 12-1) for more information.

Note 1:	The comparator synchronized output should not be used to gate the external Timer1 clock when the Timer1 synchronizer is enabled.
2:	The Timer1 prescale should be set to 1:1 when synchronizing the comparator output as unexpected results may occur with other prescale values.

The module is enabled by setting the HLVDEN bit (HLVDCON<4>). Each time the HLVD module is enabled, the circuitry requires some time to stabilize. The IRVST bit (HLVDCON<5>) is a read-only bit used to indicate when the circuit is stable. The module can only generate an interrupt after the circuit is stable and IRVST is set.

The VDIRMAG bit (HLVDCON<7>) determines the overall operation of the module. When VDIRMAG is cleared, the module monitors for drops in VDD below a predetermined set point. When the bit is set, the module monitors for rises in VDD above the set point.

23.2 Operation

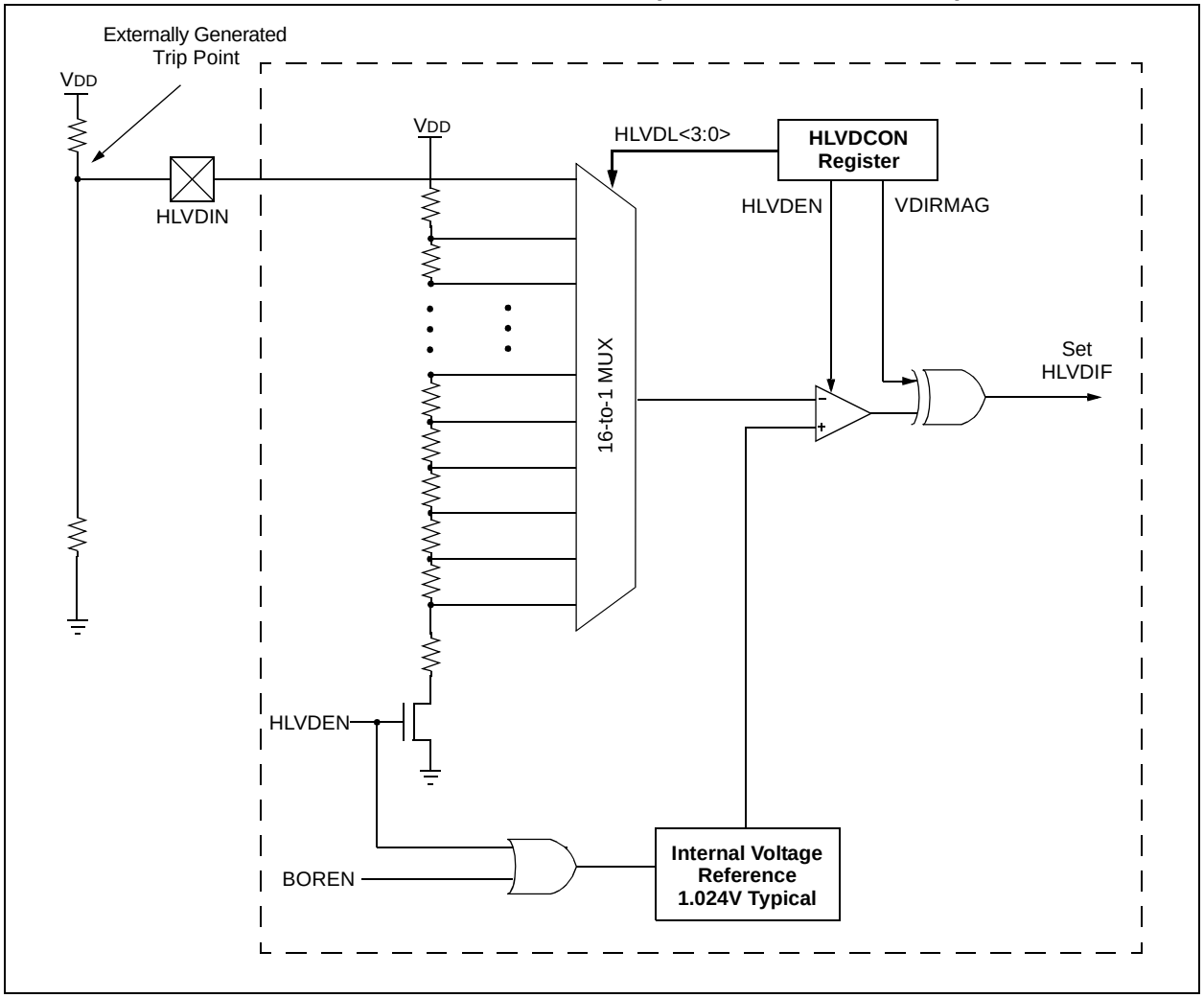
When the HLVD module is enabled, a comparator uses an internally generated reference voltage as the set point. The set point is compared with the trip point, where each node in the resistor divider represents a trip point voltage. The “trip point” voltage is the voltage level at which the device detects a high or low-voltage event, depending on the configuration of the module.

When the supply voltage is equal to the trip point, the voltage tapped off of the resistor array is equal to the internal reference voltage generated by the voltage reference module. The comparator then generates an interrupt signal by setting the HLVDIF bit.

The trip point voltage is software programmable to any of 16 values. The trip point is selected by programming the HLVDL<3:0> bits (HLVDCON<3:0>).

The HLVD module has an additional feature that allows the user to supply the trip voltage to the module from an external source. This mode is enabled when bits, HLVDL<3:0>, are set to ‘1111’. In this state, the comparator input is multiplexed from the external input pin, HLVDIN. This gives users the flexibility of configuring the High/Low-Voltage Detect interrupt to occur at any voltage in the valid operating range.

FIGURE 23-1: HLVD MODULE BLOCK DIAGRAM (WITH EXTERNAL INPUT)



27.2 DC Characteristics: Power-Down Current, PIC18(L)F2X/4XK22 (Continued)

PIC18LF2X/4XK22		Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C						
PIC18F2X/4XK22		**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +125°C						
Param No.	**Device Characteristics**	**Typ +25°C**	**Typ +60°C**	**Max +85°C**	**Max +125°C**	**Units**	**Conditions**	
							VDD	**Notes**
D015	Comparators	7	7	18	18	µA	1.8V	LP mode
		7	7	18	18	µA	3.0V	
		7	7	18	18	µA	2.3V	
		7	7	18	18	µA	3.0V	
		8	8	20	20	µA	5.0V	
D016	Comparators	38	38	95	95	µA	1.8V	HP mode
		40	40	105	105	µA	3.0V	
		39	39	95	95	µA	2.3V	
		40	40	105	105	µA	3.0V	
		40	40	105	105	µA	5.0V	
D017	DAC	14	14	25	25	µA	2.0V	
		20	20	35	35	µA	3.0V	
		15	15	30	30	µA	2.3V	
		20	20	35	35	µA	3.0V	
		32	32	60	60	µA	5.0V	
D018	FVR(2)	15	16	25	25	µA	1.8V	
		15	16	25	25	µA	3.0V	
		28	28	45	45	µA	2.3V	
		31	31	55	55	µA	3.0V	
		66	66	100	100	µA	5.0V	
D013	A/D Converter(3)	185	185	370	370	µA	1.8V	A/D on, not converting
		210	210	400	400	µA	3.0V	
		200	200	380	380	µA	2.3V	
		210	210	400	400	µA	3.0V	
		250	250	450	450	µA	5.0V	

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: On PIC18LF2X/4XK22 the BOR, HLVD and FVR enable internal band gap reference. With more than one of these modules enabled, the current consumption will be less than the sum of the specifications. On PIC18F2X/4XK22, the internal band gap reference is always enabled and its current consumption is included in the Power-down Base Current (IPD).

3: A/D converter differential currents apply only in Run mode. In Sleep or Idle mode both the ADC and the FRC turn off as soon as conversion (if any) is complete.

FIGURE 28-22: PIC18F2X/4XK22 TYPICAL IDD: RC_RUN LF-INTOSC 31 kHz

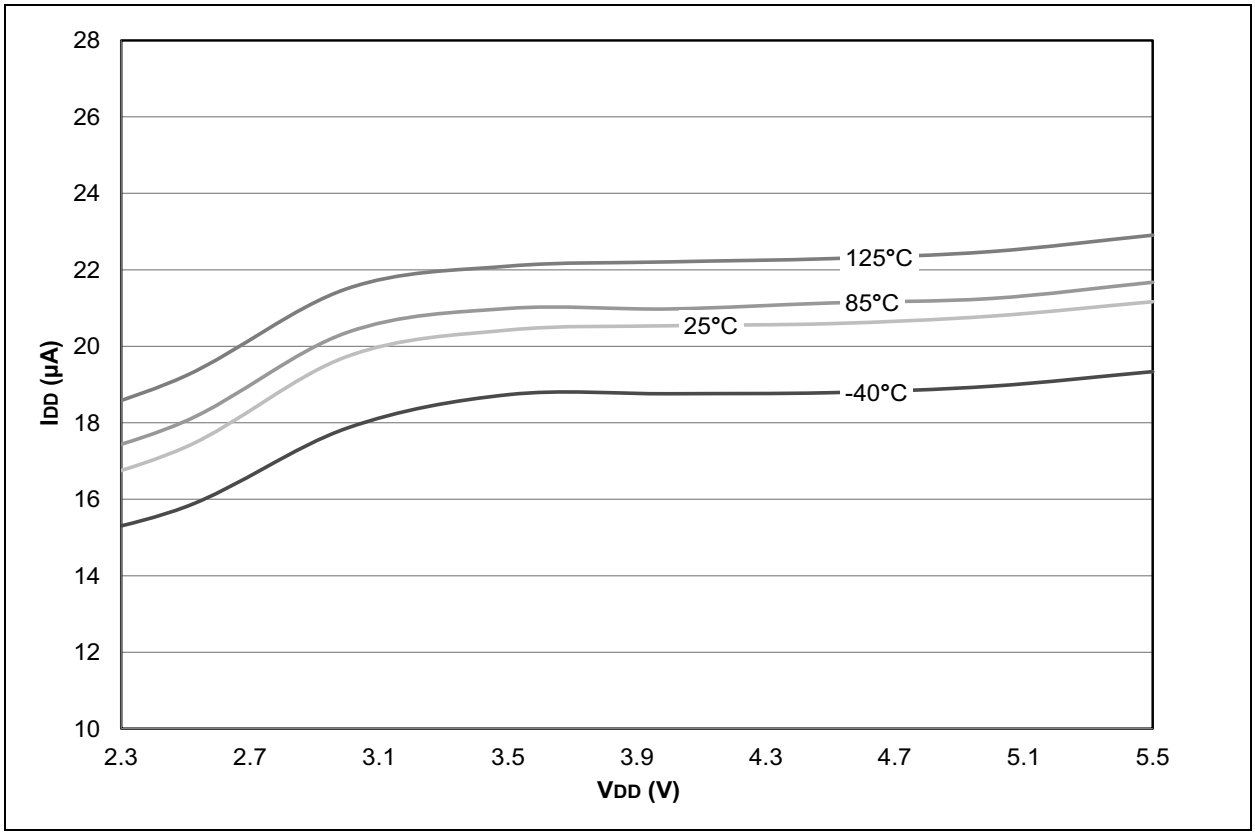


FIGURE 28-23: PIC18F2X/4XK22 MAXIMUM IDD: RC_RUN LF-INTOSC 31 kHz

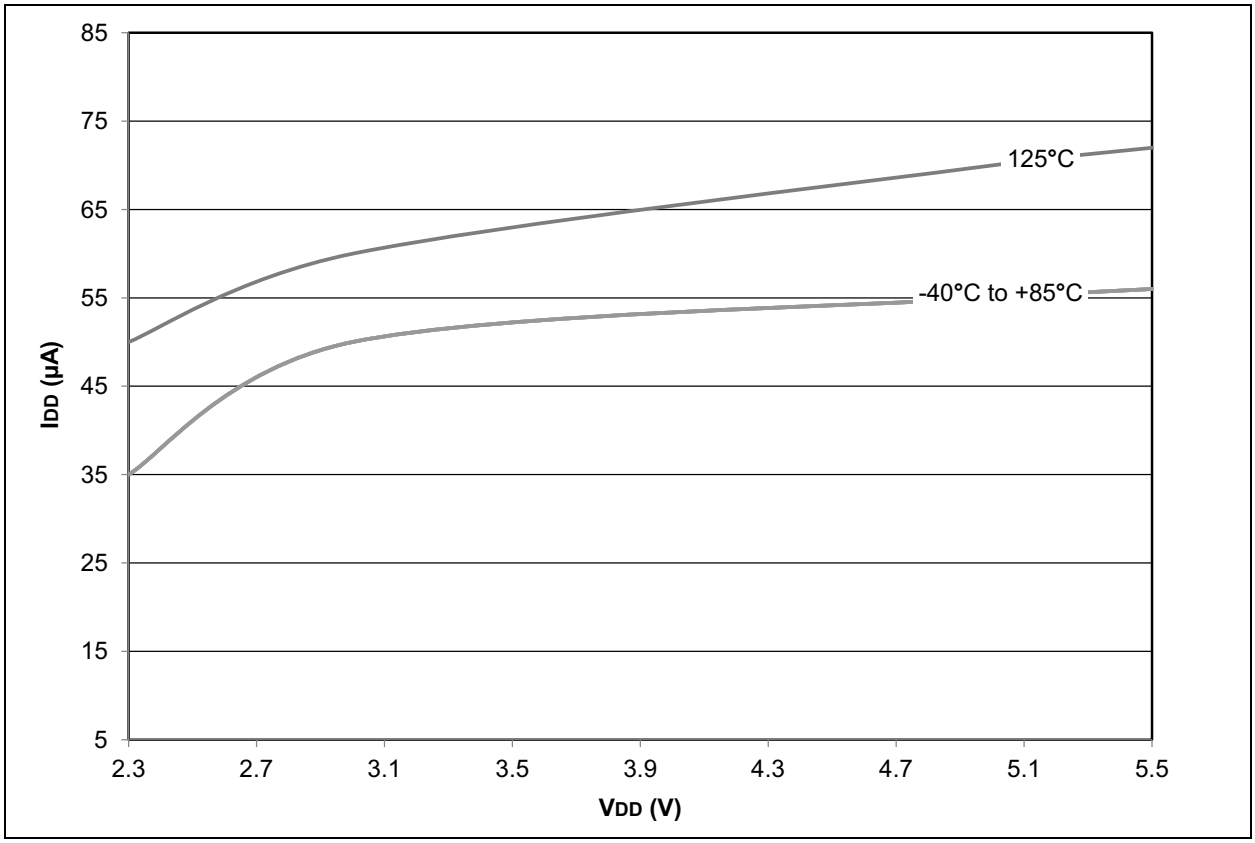


FIGURE 28-48: PIC18LF2X/4XK22 TYPICAL IDD: PRI_RUN EC MEDIUM POWER

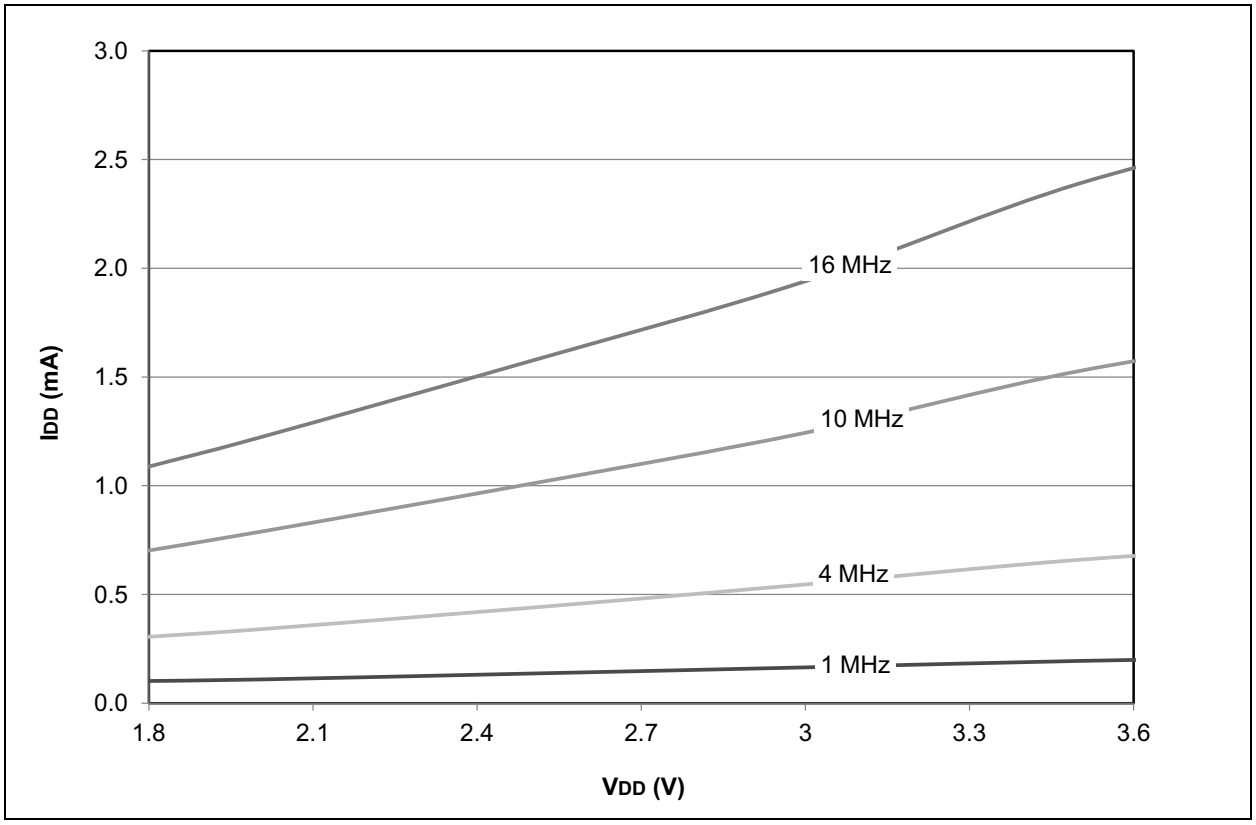
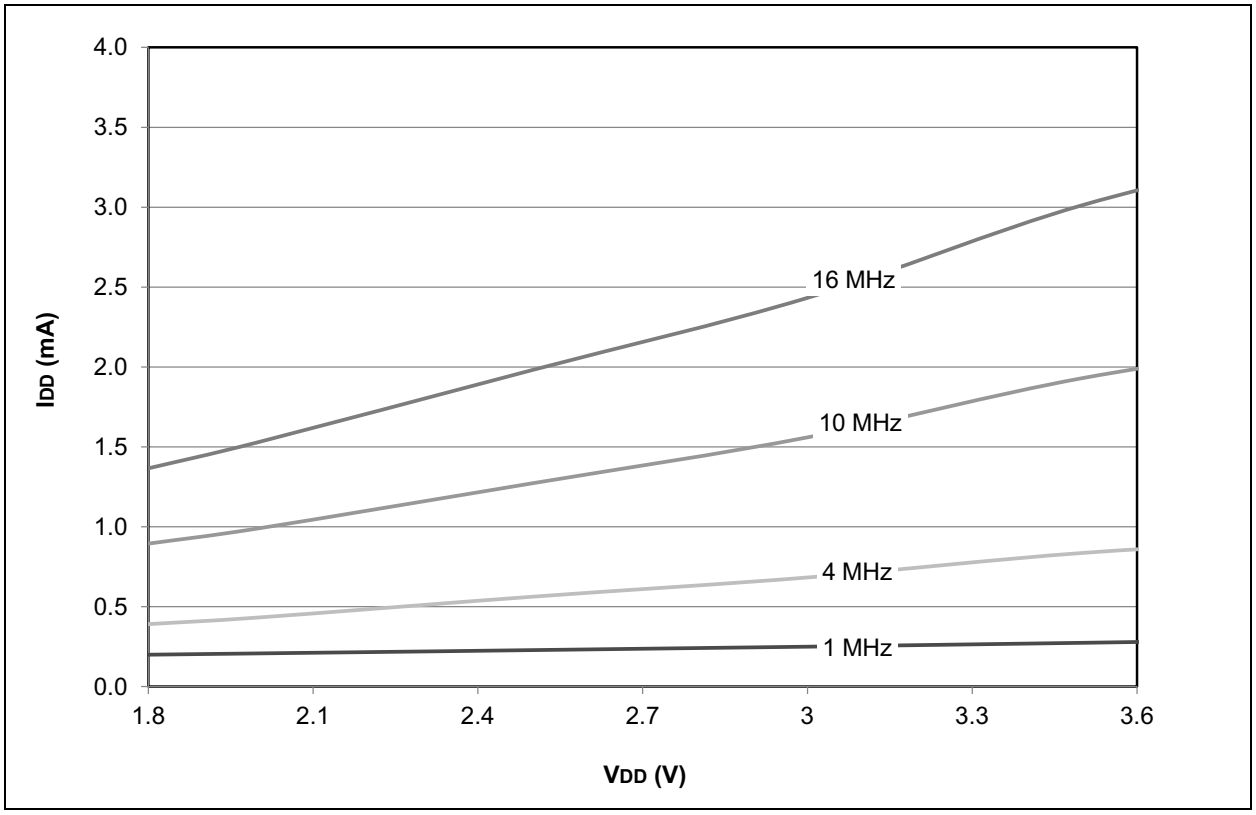
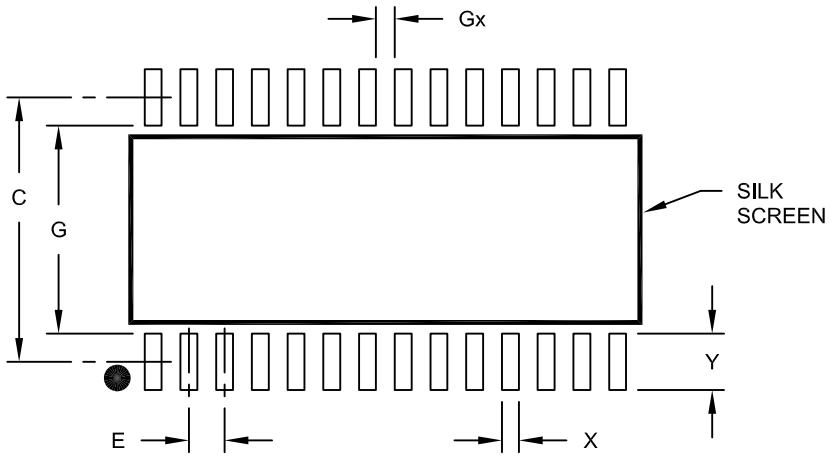


FIGURE 28-49: PIC18LF2X/4XK22 MAXIMUM IDD: PRI_RUN EC MEDIUM POWER



28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

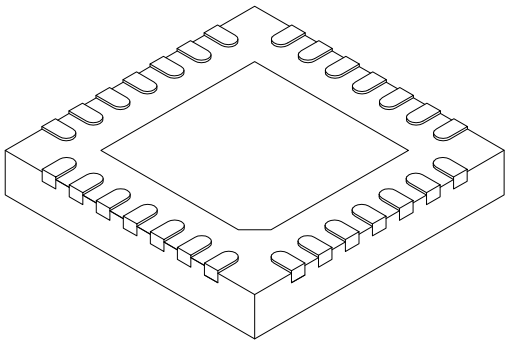
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

28-Lead Plastic Quad Flat, No Lead Package (ML) - 6x6 mm Body [QFN] With 0.55 mm Terminal Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	3.65	3.70	4.20
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	3.65	3.70	4.20
Terminal Width	b	0.23	0.30	0.35
Terminal Length	L	0.50	0.55	0.70
Terminal-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105C Sheet 2 of 2